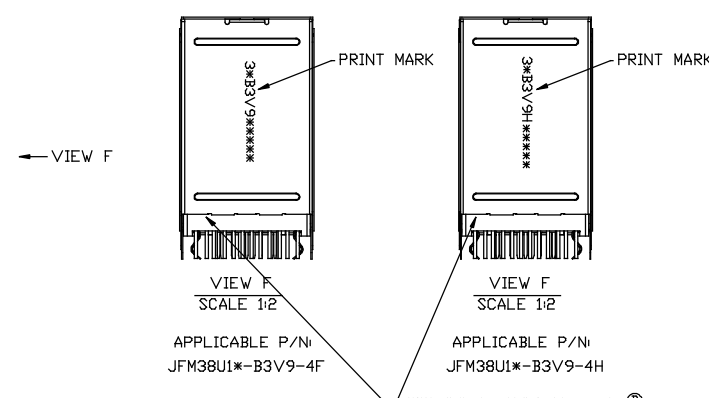
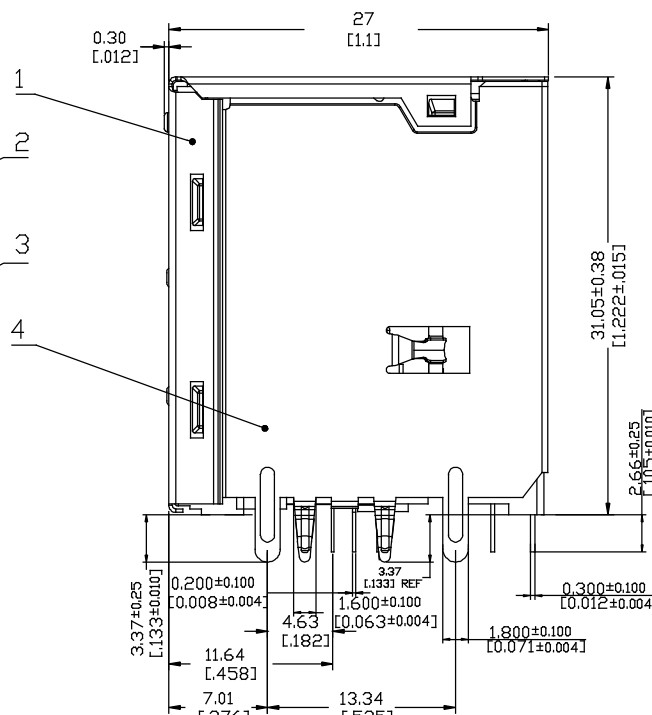
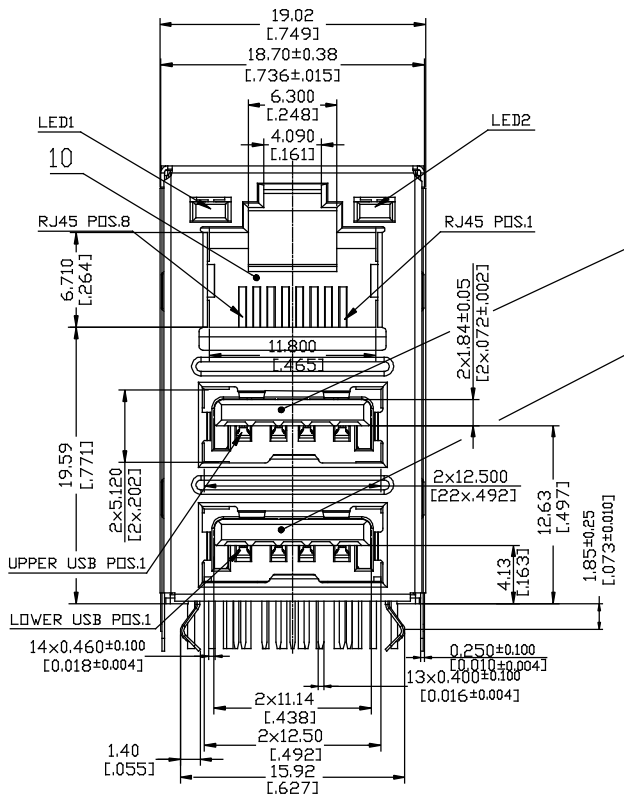
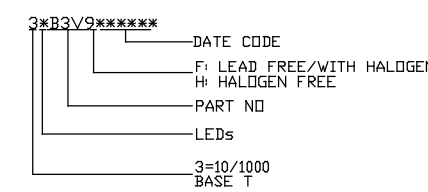


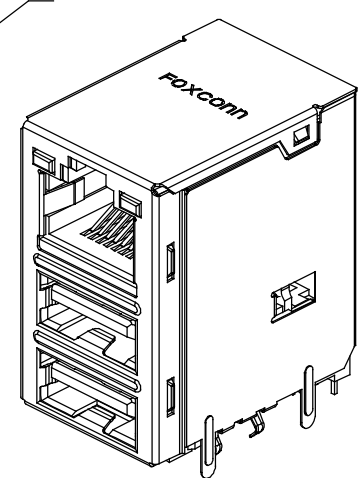
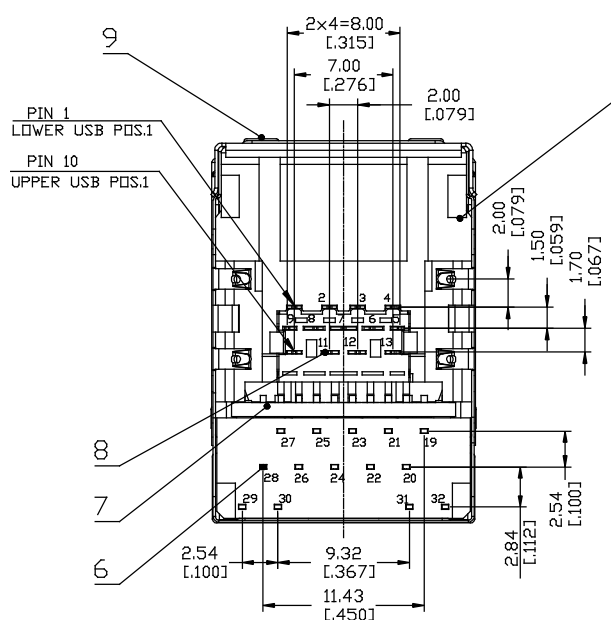
REV.	ECN. NO.	APPD.
A	BC-14-0021241	L.C. WU
B	BC-15-0010904	L.C. WU



- NOTES UNLESS OTHERWISE SPECIFIED
1. RJ45 TO BE BASED UPON FCC 68.5
  2. STACKED USB TO BE BASED UPON USB 3.0 SPECIFICATION
  3. RECOMMENDED PCB THICKNESS: 1.57±0.05 [L.062±.002]
  4. SOLDER CONDITION: WAVE SOLDER PEAK TEMPERATURE 265°C 5~10 SECOND
  5. PRINT MARK:



6. PRODUCT TO BE COMPLY WITH REQUIREMENT OF RoHS



X. ±	X*. ±	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
X ±	.X* ±	MAT'L		CUSTOMER	
.XX ± <sup>0.25</sup> [L.010]	.XX* ±		N/A	PART NO. (INTENDED USE) JFM38U1*-B3V9-4F JFM38U1*-B3V9-4H	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX* ±	FINISH		APPD: L.C. WU 03/04'15	TITLE: RJ45 MODULAR JACK OVER STACKED USB2.0+USB3.0 RECEPTACLE
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				Q'TY	DRG NO.:
					N/A
				CHKD: FEI LI 03/04'15	
				DR: SUNNY.SU 03/04'15	

10	RJ45 CONTACT	8	PHOSPHOR BRONZE	30u" MIN. FPT PLATING AT CONTACT FUNCTION AREA 100~200u" LEAD FREE TIN PLATING AT SOLDERING AREA 50~100u" NICKEL UNDERPLATING
9	LIGHTER	2	LED	LED1 X 1 LED2 X 1
8	USB CONTACT	13	PHOSPHOR BRONZE	30u" MIN. FPT PLATING AT CONTACT FUNCTION AREA 100~200u" LEAD FREE TIN PLATING AT SOLDERING AREA 50~100u" NICKEL UNDERPLATING
7	TRANSFORMER MODULE	1		
6	FOOT CONTACT	14	BRASS	100~200 u" LEAD FREE TIN PLATING ALL 50~100u" NICKEL UNDERPLATING
5	FRAME HOUSING	1	UL 94V-0	MOLDED COLOR: BLACK
4	REAR SHELL	1	STAINLESS STEEL	50~100u" NICKEL UNDERPLATING, 50~200u" Sn PLATED AT TAB AREA
3	USB3 INSERT HOUSING	1	UL 94V-0	MOLDED COLOR: BLACK, PANTONE 300C
2	USB2 HOUSING	1	UL 94V-0	MOLDED COLOR: BLACK
1	FRONT SHELL	1	STAINLESS STEEL	CLEANING
ITEM	DESC.	Q'TY	MATERIAL	TREATMENT

REMARK:

JFM  
RJ WITH MAGNETIC

3  
PROTOCOL TYPE:  
3=10/100/1000  
BASE T

8  
CORE COUNT:  
8=8 CORE

U  
CONFIGURATION:  
U=COMBO USB

1  
PCB ATTACH METHOD  
1=SOLDER  
TAIL

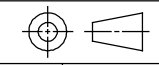
\*  
LEDs  
(SEE SHEET 3/5)

— B 3 V 9  
EXTENSION NO.

4  
PACKAGING  
4: SOFT TRAY

\*  
MATERIAL:  
H: HALOGEN FREE  
F: LEAD FREE/WITH HALOGEN

X. ±	X* ±	UNITS	mm	NAME(INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
X ±	X* ±	MAT'L	N/A	CUSTOMER	
.XX ±	.XX* ±	FINISH	N/A	PART NO.(INTENDED USE) JFM38U1*-B3V9-4F JFM38U1*-B3V9-4H	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX±	.XXX*±	Q'TY	N/A	APPD: L.C. WU 03/04'15	TITLE: RJ45 MODULAR JACK OVER STACKED USB2.0+USB3.0 RECEPTACLE
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				CHKD: FEI LI 03/04'15	DWG NO: 305-0000-5577
				DR: SUNNY.SU 03/04'15	SCALE SHEET REV. N/A 2/5 B



NOTES :UNLESS OTHERWISE SPECIFIED

7. ALL SHIELDING PINS TO BE CONNECTED TO SHELL GROUNDING.

8. ELECTRICAL SPECIFICATIONS @ 25°C:

8.1 HI-POT<ISOLATION VOLTAGE>: 1500VRMS FOR RJ PORT  
500VRMS FOR USB CONTACT TO CONTACT

8.2 PRIMARY INDUCTANCE<OCL> :350uH: MIN.  
@ 100KHz/100mVRMS,8mA DC BIAS

8.3 TURNS RATIO: PRIMARY:SECONDARY 1:1 ±2%

8.4 HIGH FREQUNCY INSERTION LOSS: 1-100 MHz , -1.2dB MAX

RETURN LOSS: 1-40 MHz, -18dB MIN.  
40-100MHz, -12+20log(F/80)dB MIN.

CROSS TALK: 1-100 MHz, -30dB MIN.

CMRR: 1-100 MHz, -30dB MIN.

DCMR: 1-100 MHz, -30dB MIN.

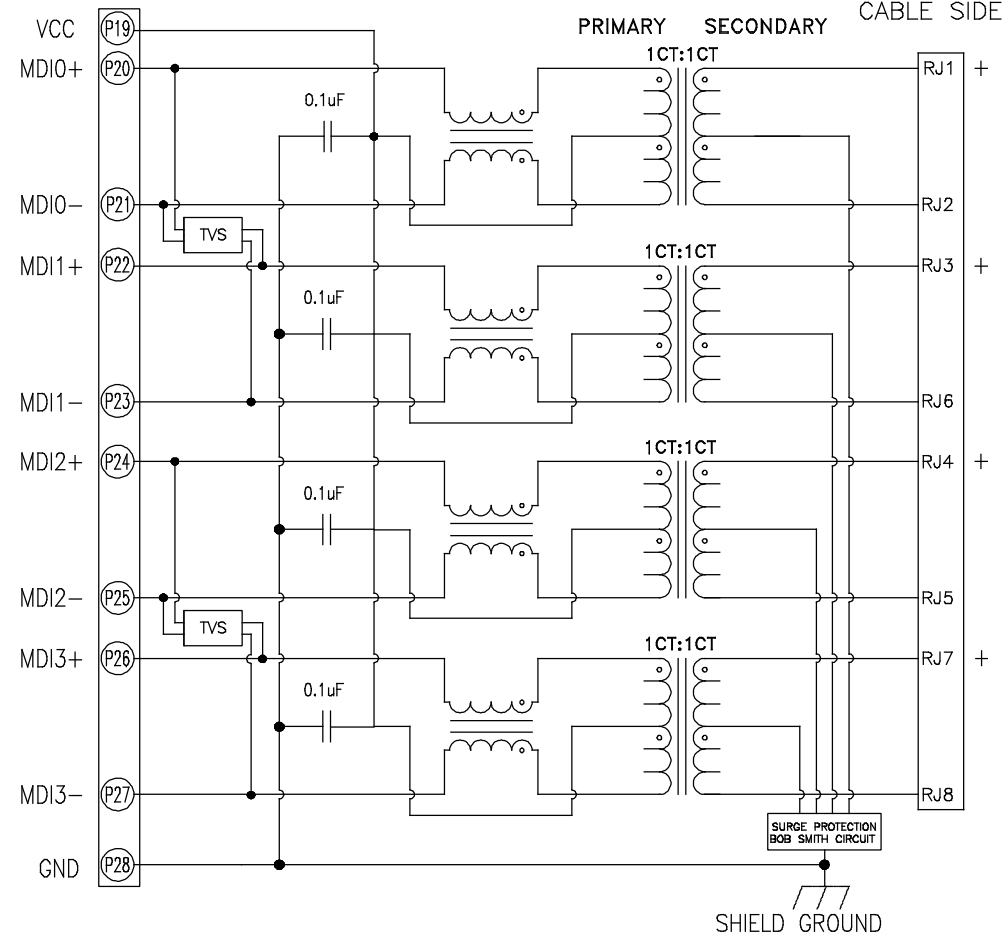
9. SURGE PROTECTION:TEST WAVEFORM OF OPEN-CIRCUIT VOLTAGE 10/700uS

LINE-LINE:±2KV,LINE-GND:±6KV

LANCHIP SIDE

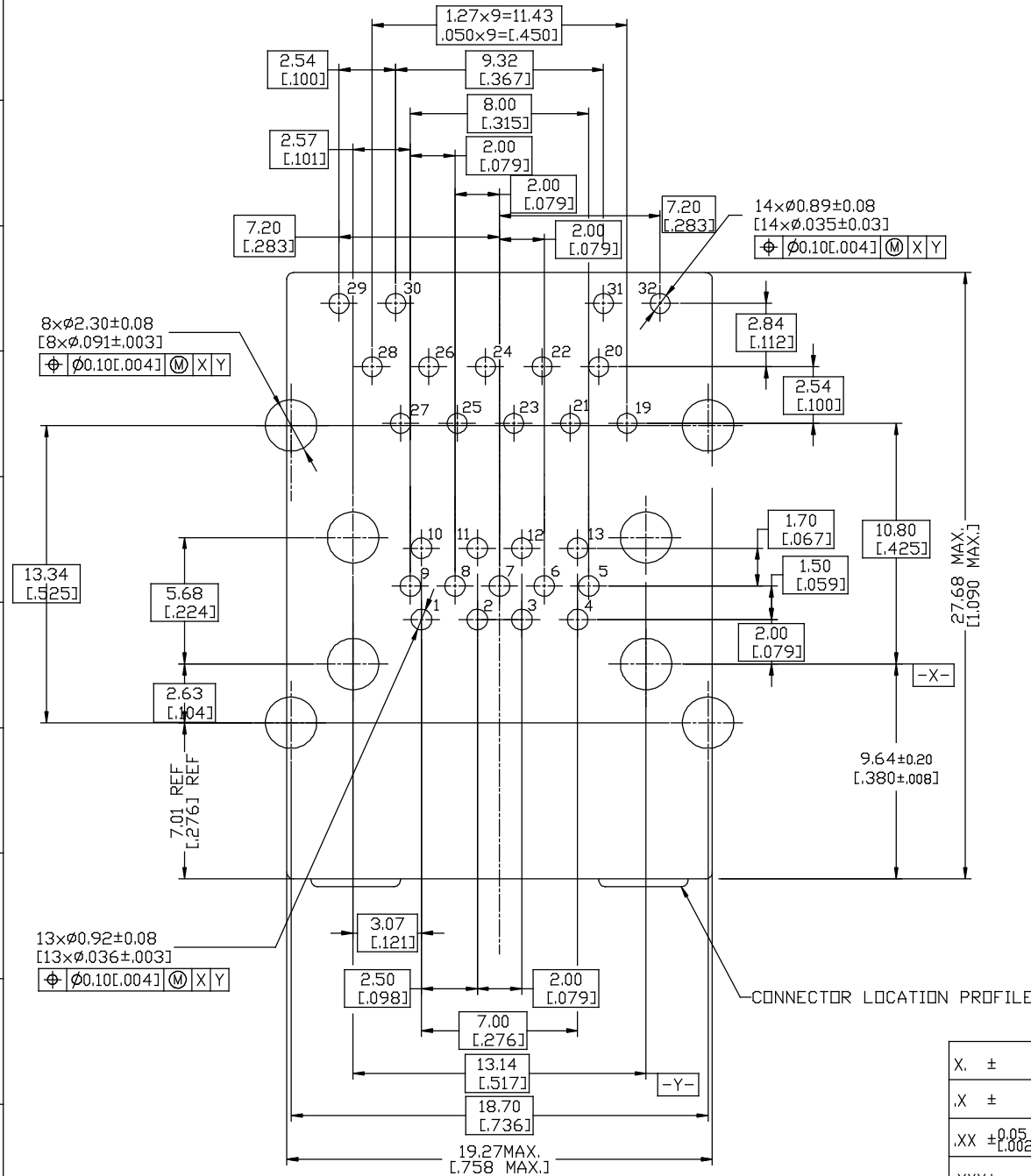
SCHEMATIC

CABLE SIDE



JFM38U1M-B3V9-4*	29 YELLOW	30	ORANGE	31	32
JFM38U1K-B3V9-4*	29 ORANGE	30	GREEN	31	32
JFM38U1J-B3V9-4*	29 GREEN	30	GREEN	31	32
JFM38U1H-B3V9-4*	29 ORANGE	30	GREEN	31	32
JFM38U1G-B3V9-4*	29 YELLOW	30	GREEN	31	32
JFM38U1F-B3V9-4*	29 GREEN	30	ORANGE	31	32
JFM38U1B-B3V9-4*	29 GREEN	30	YELLOW	31	32
JFM38U1A-B3V9-4*	29 GREEN	30	YELLOW	31	32
JFM38U14-B3V9-4*	29 YELLOW	30	YELLOW	31	32
JFM38U13-B3V9-4*	29 GREEN	30	YELLOW	31	32
JFM38U12-B3V9-4*	29 GREEN	30	GREEN	31	32
JFM38U11-B3V9-4*	29 YELLOW	30	GREEN	31	32
JFM38U10-B3V9-4*	NONE		NONE		
PART NO.	LED1		LED2		

X. ±	X*. ±	UNITS	mm	NAME<INTENDED USE>	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
X ±	.X* ±	MAT'L		CUSTOMER	
.XX ±	.XX* ±		N/A	PART NO.<INTENDED USE>	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX±	.XXX*±	FINISH		JFM38U1*-B3V9-4F JFM38U1*-B3V9-4H	TITLE: RJ45 MODULAR JACK OVER STACKED USB2.0+USB3.0 RECEPTACLE
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				APPD: L.C. WU 03/04'15	DWG NO: 305-0000-5577
		Q'TY		CHKD: FEI LI 03/04'15	SCALE SHEET REV. N/A 3/5 B
				DR: SUNNY.SU 03/04'15	

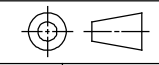


USB2.0 + USB3.0 STANDARD-A CONNECTOR PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	DESCRIPTION
1 10	VBUS	POWER
2 11	D-	USB 2.0 DIFFERENTIAL PAIR
3 12	D+	
4 13	GND	GROUND FOR POWER RETURN
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR
6	StdA_SSRX+	
7	GND_DRAIN	GROUND FOR SIGNAL RETURN
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR
9	StdA_SSTX+	

CONNECTOR LOCATION PROFILE

X. ±	X* ±	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
X ±	X* ±	MAT'L	N/A	CUSTOMER	
.XX ± <sup>0.05</sup> <sub>[0.02]</sub>	.XX* ±	FINISH	N/A	PART NO. (INTENDED USE) JFM38U1*-B3V9-4F JFM38U1*-B3V9-4H	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX* ±	Q'TY	N/A	APPD: L.C. WU 03/04'15	TITLE: RJ45 MODULAR JACK OVER STACKED USB2.0+USB3.0 RECEPTACLE
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				CHKD: FEI LI 03/04'15	DWG NO: 305-0000-5577
				DR: SUNNY.SU 03/04'15	SCALE SHEET REV. N/A 4/5 B



NOTES :UNLESS OTHERWISE SPECIFIED

RJ45 SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:

- 1-1. CURRENT RATING: 1.5 AMPERES MAXIMUM.
- 1-2. INSULATION RESISTANCE: 500 MEGAOHMS MINIMUM.
- 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 1000 Vrms CONTACT TO CONTACT.

1-4. LED'S CHARACTERISTICS:

- 1-4-1. POWER DISSIPATION: 80 mW MAX.
- 1-4-2. FORWARD CURRENT: 30 mA MAX.
- 1-4-3. FORWARD VOLTAGE: 2.2 VOLTS TYPICAL.
- 1-4-4. REVERSE VOLTAGE: 5.0 VOLTS MAX.
- 1-4-5. PEAK EMISSION WAVELENGTH: GREEN LED: 565 nm TYPICAL.  
YELLOW LED: 589 nm TYPICAL.
- 1-4-6. ANODE  $\rightarrow$  CATHODE ORANGE LED: 604 nm TYPICAL.

2. MECHANICAL CHARACTERISTICS:

- 2-1. CONNECTOR MATING FORCES: 4.5LBS MAXIMUM WITH LATCH DEPRESSED,  
CONNECTOR UNMATING FORCE: 4.5LBS MAXIMUM WITH LATCH DEPRESSED AT AN ADVANTAGEOUS ANGLE.
- 2-2. DURABILITY (MATING/UNMATING CYCLES): 1000 CYCLES.
- 2-3. OPERATING TEMPERATURE: -30°C TO +85°C,  
STORAGE TEMPERATURE: -40°C TO +100°C.

USB SPECIFICATIONS:

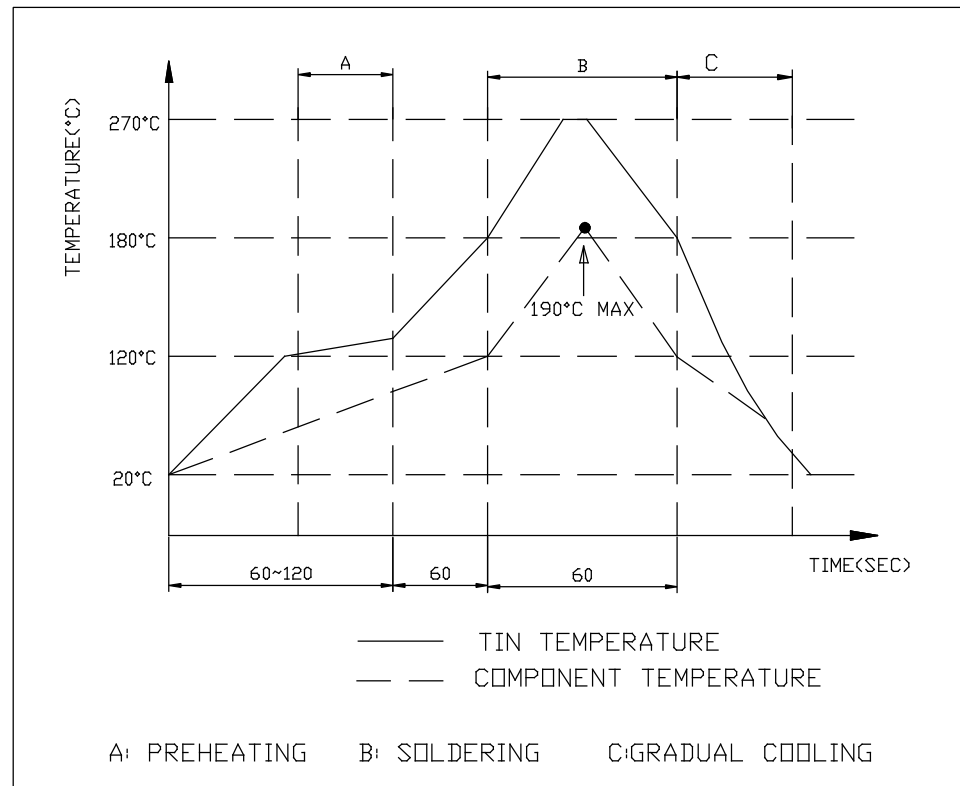
1. ELECTRICAL CHARACTERISTICS:

- 1-1.CONTACT CURRENT RATING:1 AMPERE .
- 1-2.CONTACT RESISTANCE:30 mOHMS MAX..
- 1-3.DIELECTRIC WITHSTANDING VOLTAGE:500 VAC MIN.,
- 1-4.INSULATION RESISTANCE:1000 MOHMS MIN.,

2. MECHANICAL CHARACTERISTICS:

- 2-1.CONNECTOR MATING FORCE : 3.5 Kgf MAX.,
- 2-2.CONNECTOR UNMATING FORCE : 1.0 Kgf MIN.,
- 2-3.DURABILITY : 1500 CYCLES.
- 2-4.OPERATING TEMPERATURE: -55 TO +85 °C

PROFILE OF WAVE SOLDER:



SUGGESTED WAVE SOLDER CURVE

- (1) PEAK TEMPERATURE: 265±5°C
- (2) PEAK TEMPERATURE TIME: 5~10 SECOND

X. ±	X* ±	UNITS mm	NAME(INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			
X ±	X* ±	MAT'L	CUSTOMER				
.XX ±	.XX* ±	N/A	PART NO.(INTENDED USE) JFM38U1*-B3V9-4F JFM38U1*-B3V9-4H	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL			
.XXX±	.XXX*±	FINISH	APPD: L.C. WU 03/04'15	TITLE:RJ45 MODULAR JACK OVER STACKED USB2.0+USB3.0 RECEPTACLE			
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			Q'TY	CHKD: FEI LI 03/04'15	DWG NO: 305-0000-5577		
			N/A	DR: SUNNY.SU 03/04'15	SCALE	SHEET	REV.
					N/A	5/5	B